## **Enabling 3D: Temporary Bonding Workshop 2011**

San Francisco, California, USA 11 July 2011

ISBN: 978-1-61839-392-0

## Printed from e-media with permission by:

Curran Associates, Inc. 57 Morehouse Lane Red Hook, NY 12571



Some format issues inherent in the e-media version may also appear in this print version.

Copyright© (2011) by SEMATECH All rights reserved.

Printed by Curran Associates, Inc. (2012)

For permission requests, please contact SEMATECH at the address below.

SEMATECH 2706 Montopolis Drive Austin, Texas 78741

Phone: (512) 356-3500 Fax: (512) 356-7848

www.sematech.org

## Additional copies of this publication are available from:

Curran Associates, Inc. 57 Morehouse Lane Red Hook, NY 12571 USA Phone: 845-758-0400

Phone: 845-758-0400 Fax: 845-758-2634

Email: curran@proceedings.com Web: www.proceedings.com

## **Enabling 3D: Temporary Bonding Workshop**

July 11, 2011 San Francisco, CA

| Welcome & Introduction                                                 | Sitaram Arkalgud, SEMATECH  | 1  |
|------------------------------------------------------------------------|-----------------------------|----|
| Temporary Bond Material and Process: Survey Drivers and Reference Flow | Myung Jin Yim, SEMATECH     | 7  |
| 3D TSV Temporary Bonding Survey Responses                              | Myung Jin Yim, SEMATECH     | 14 |
| Temporary Bonding – HVM Concerns                                       | Markus Wimplinger, EV Group | 23 |